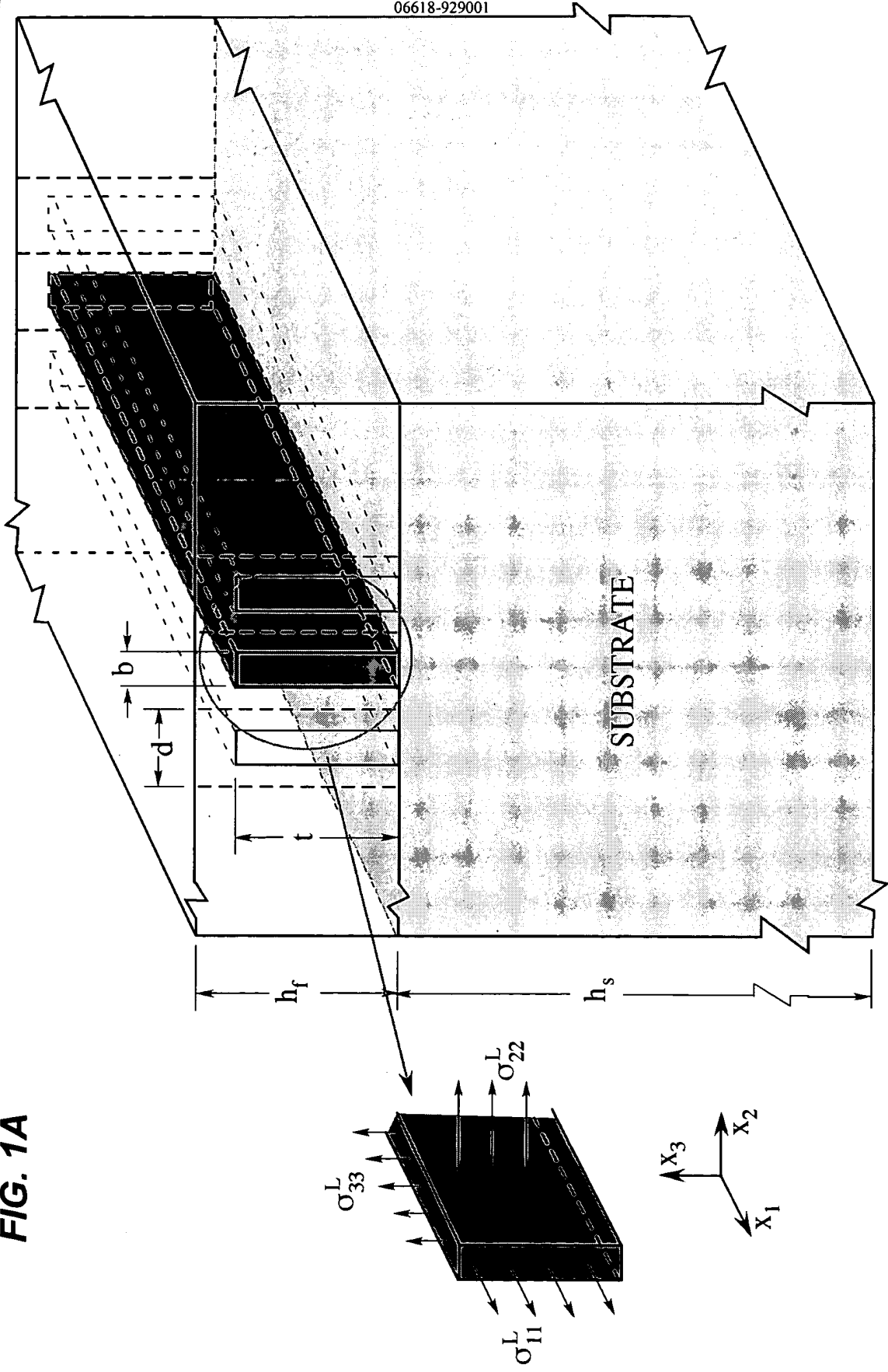
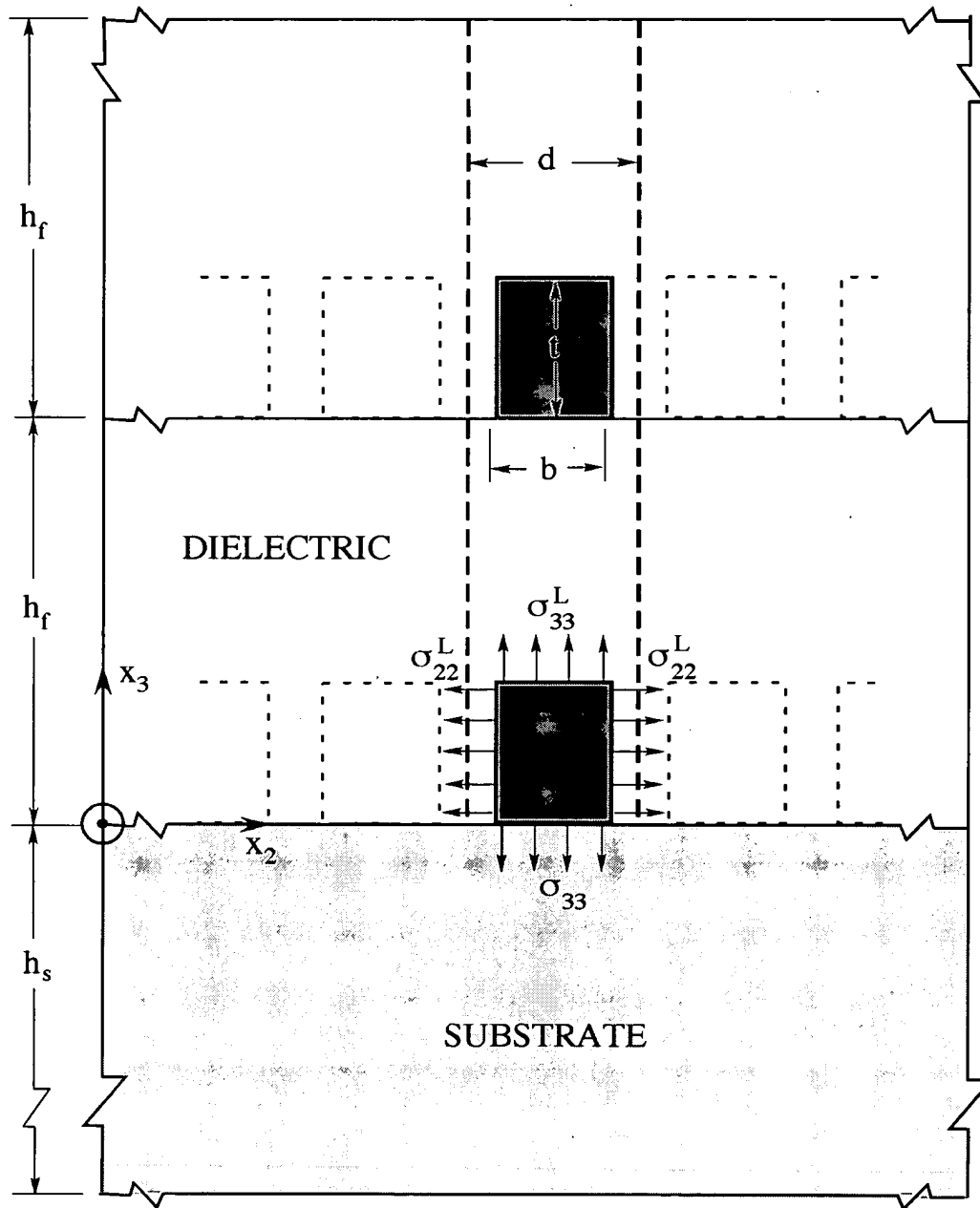


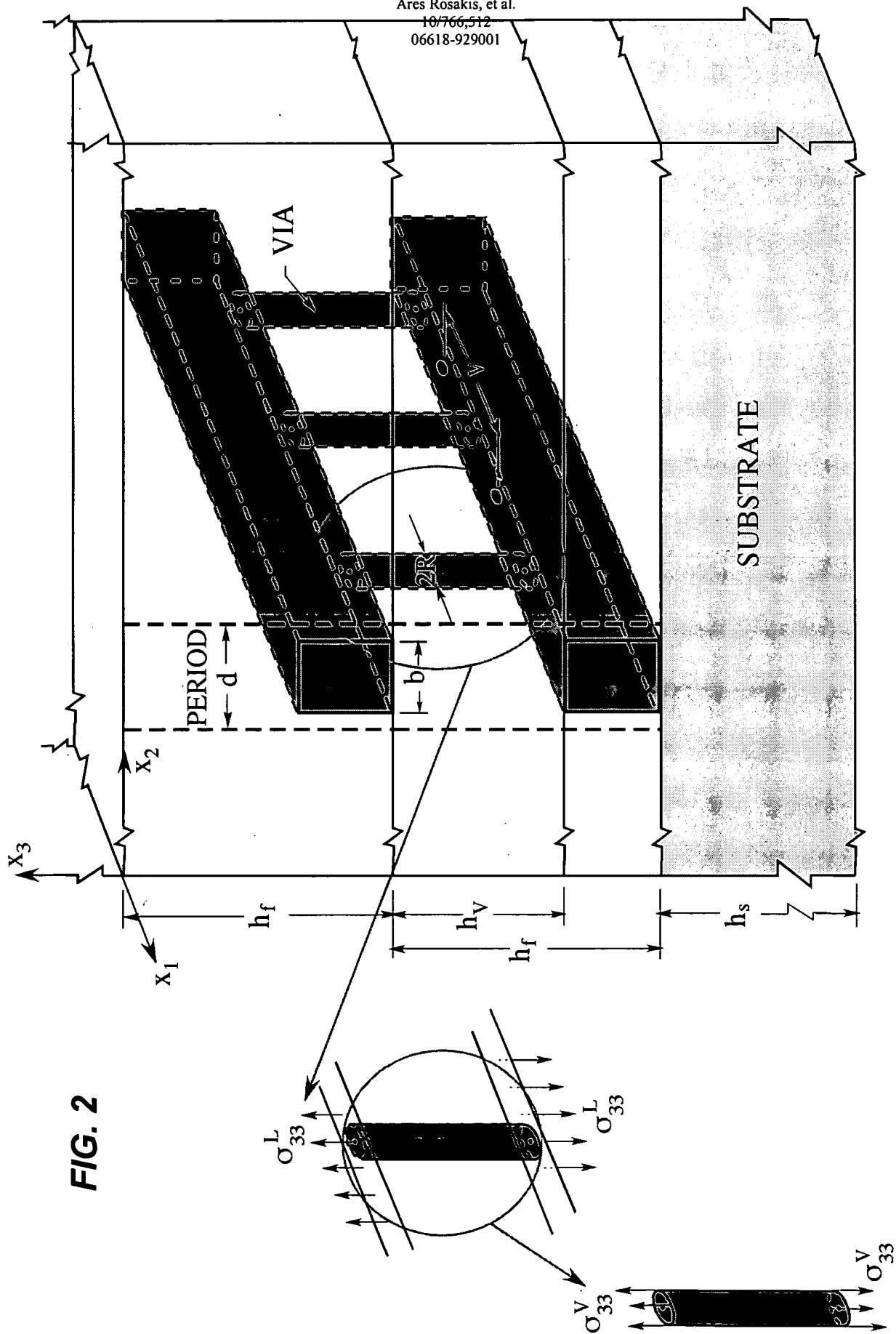


FIG. 1A



**FIG. 1B**

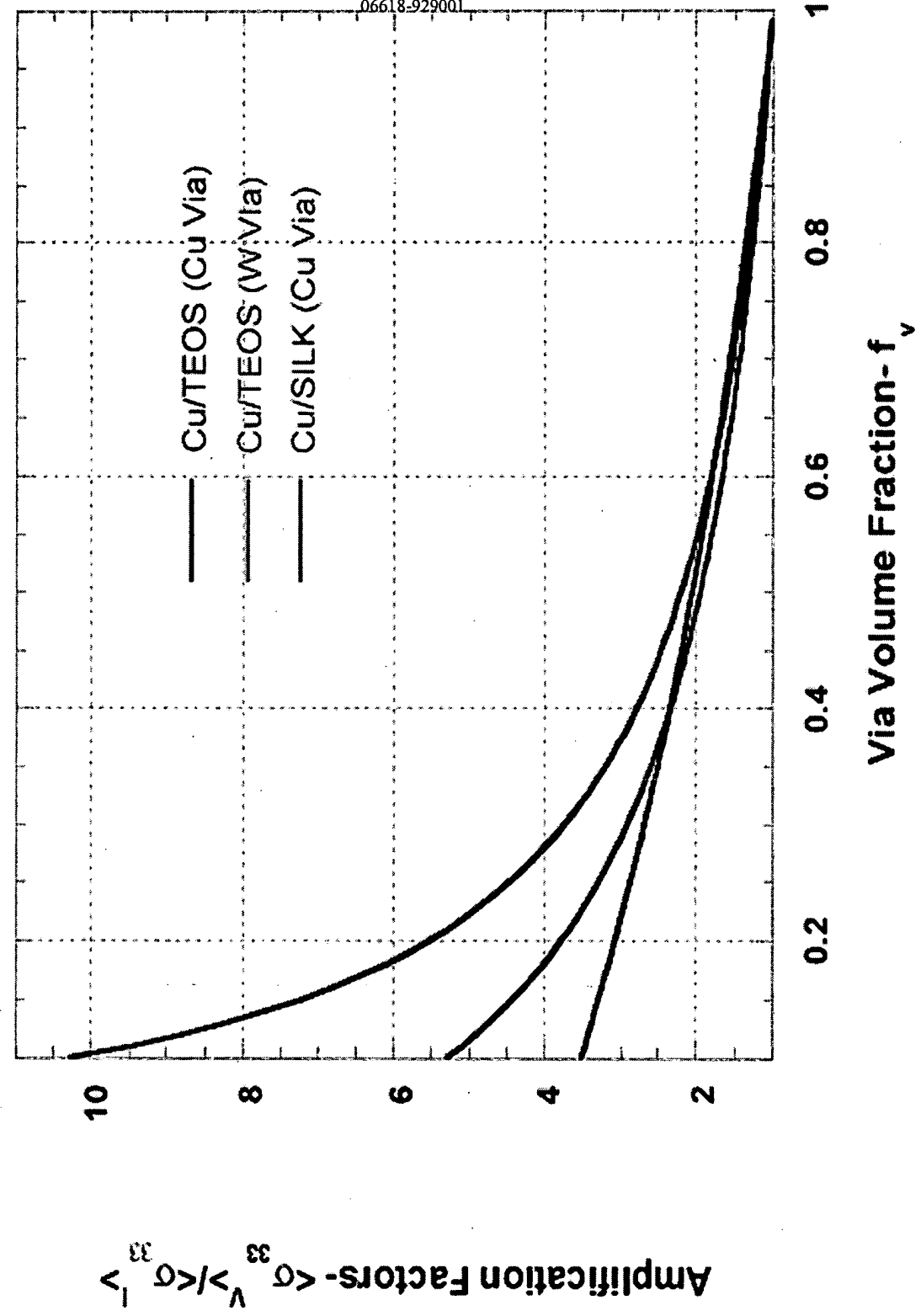




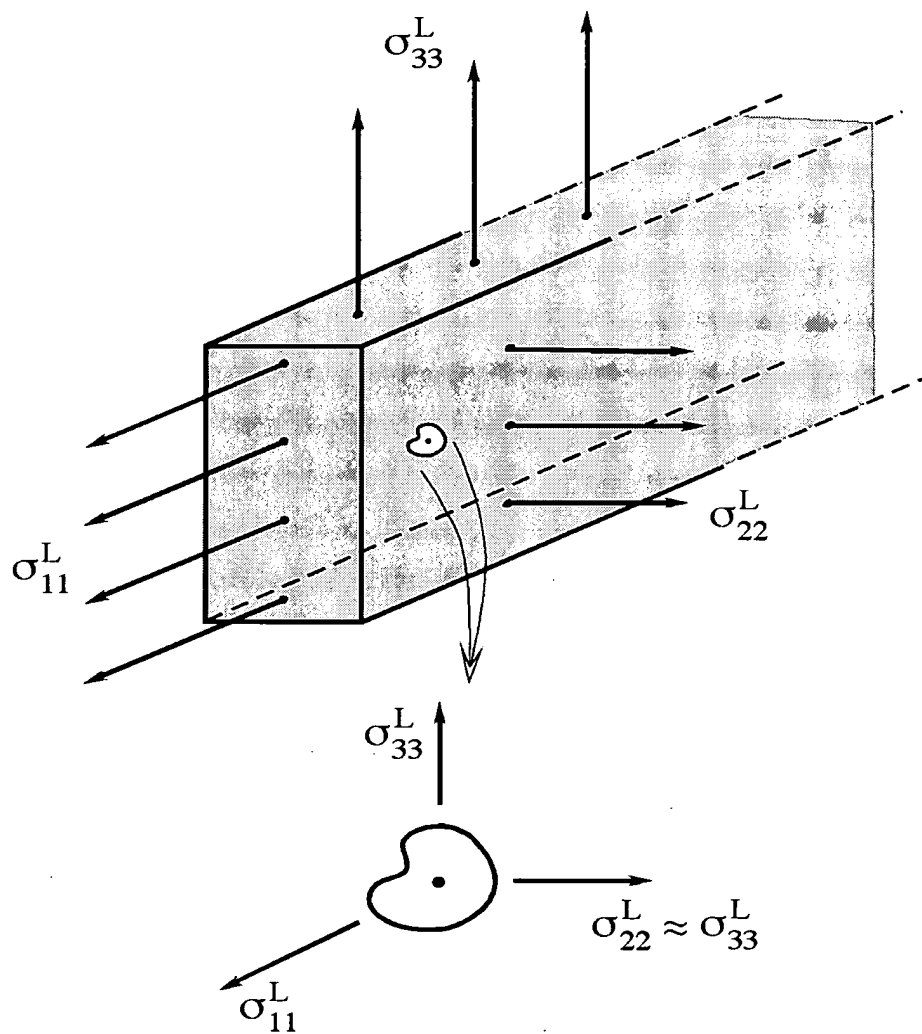
10/766,512  
 06618-929001

$E_{Cu} = 110 \text{ GPa}, \alpha_{Cu} = 17 \times 10^{-6} / ^\circ\text{C}$   
 $E_W = 410 \text{ GPa}, \alpha_W = 4.3 \times 10^{-6} / ^\circ\text{C}$   
 $E_{TEOS} = 59 \text{ GPa}, \alpha_{TEOS} = 1 \times 10^{-6} / ^\circ\text{C}$   
 $E_{SILK} = 2.45 \text{ GPa}, \alpha_{SILK} = 66 \times 10^{-6} / ^\circ\text{C}$

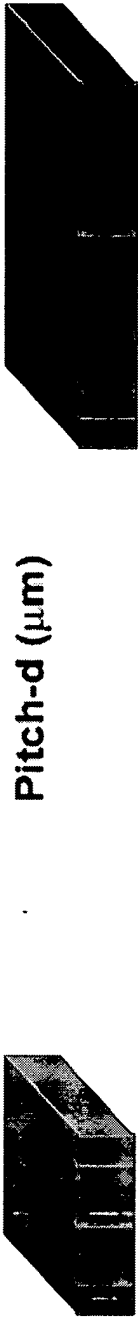
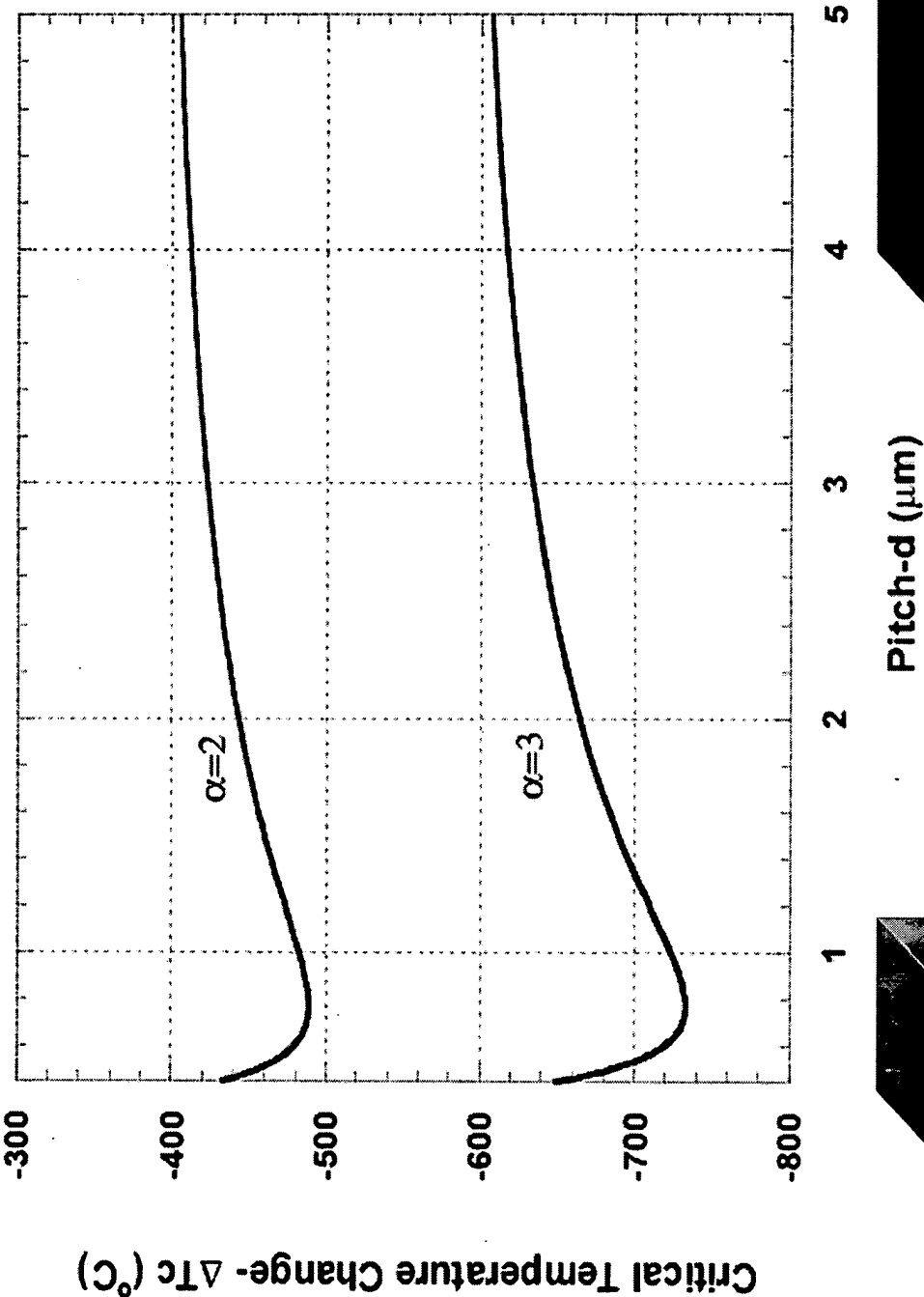
FIG. 3



**FIG. 4**



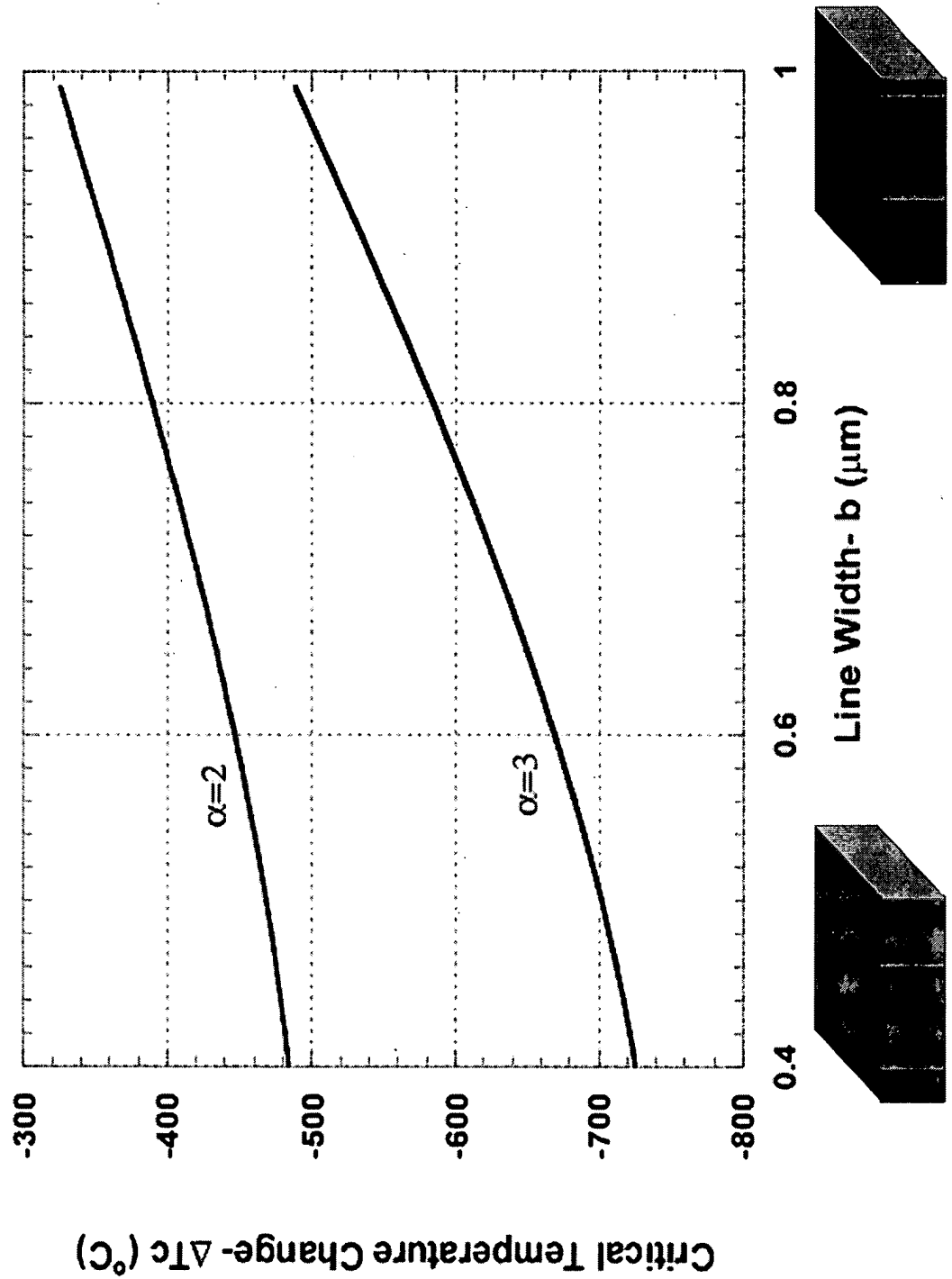
**Materials:** Cu lines, TEOS dielectric, Si Substrate  
**Geometry:**  $t=0.5\mu\text{m}$ ,  $h_s=525\mu\text{m}$ ,  $b=0.4\mu\text{m}$ ,  $f_i=b/d$   
**Criterion:**  $\alpha=2$  or  $3$ ,  $\sigma_y=293\text{MPa}$  (using Hall-Petch)



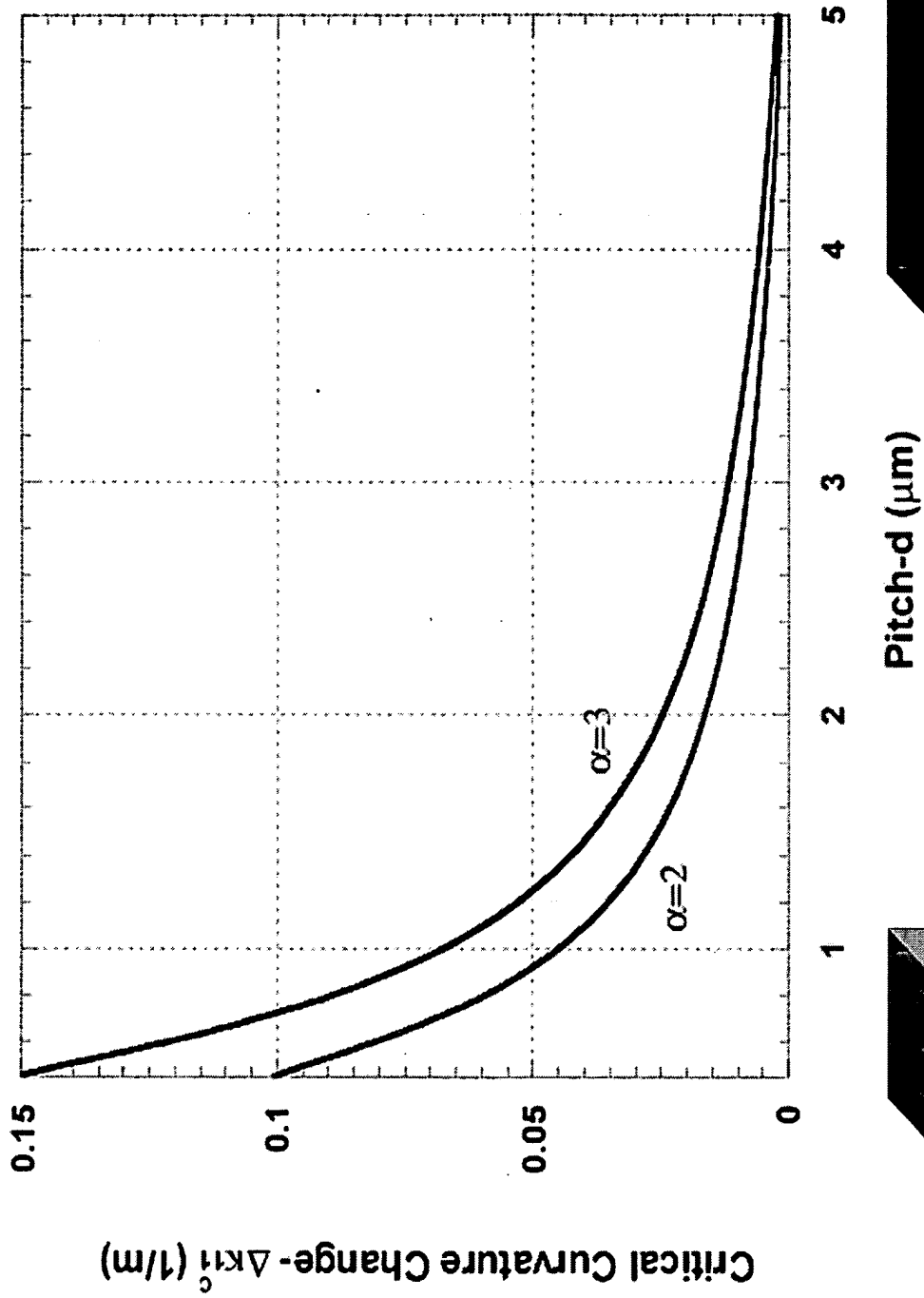
**FIG. 5**

**Materials:** Cu lines, TEOS dielectric, Si Substrate  
**Geometry:**  $t=0.5\mu\text{m}$ ,  $h_s=525\mu\text{m}$ ,  $d=1.0\mu\text{m}$ ,  $f_1=b/d$   
**Criterion:**  $\alpha=2$  or  $3$ ,  $\sigma_y = 26.9[1+6.64\{(t+b)/2\}^{-0.5}] \text{ MPa}$

**FIG. 6**



**Materials:** Cu lines, TEOS dielectric, Si Substrate  
**Geometry:**  $t=0.5\mu\text{m}$ ,  $h_s=525\mu\text{m}$ ,  $b=0.4\mu\text{m}$ ,  $f_l=b/d$   
**Criterion:**  $\alpha=2$  or  $3$ ,  $\sigma_y=293\text{MPa}$  (using Hall-Petch)

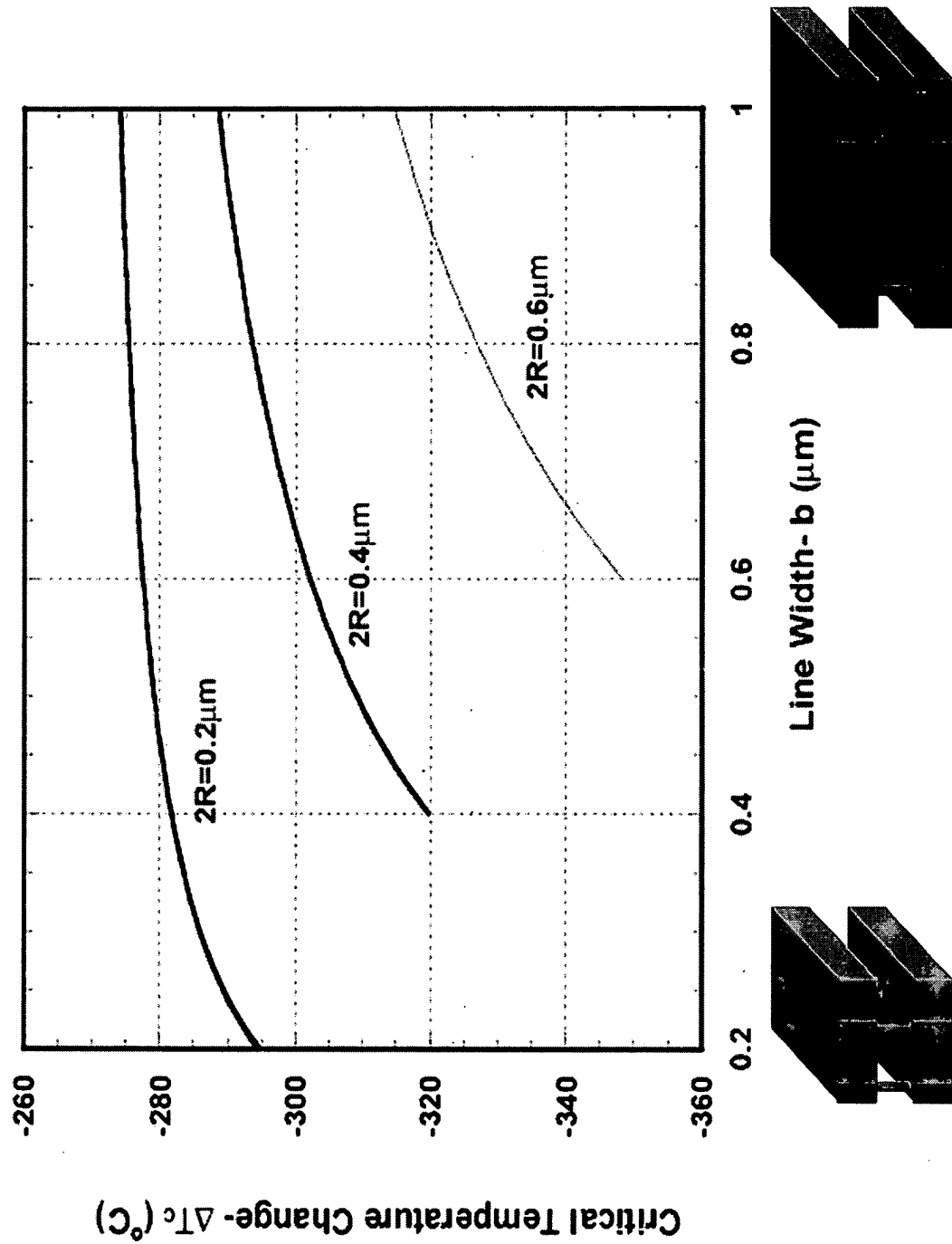


**FIG. 7**



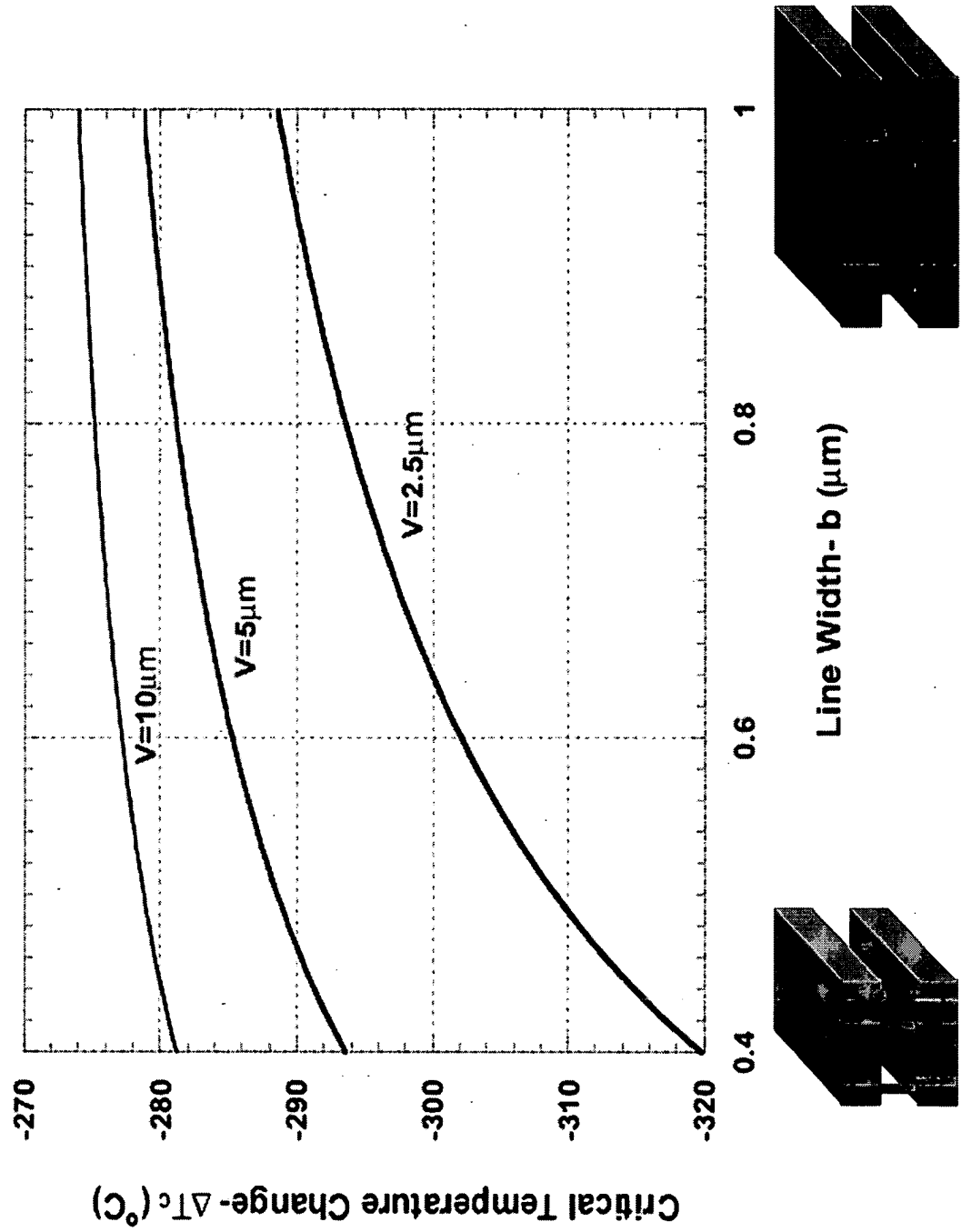
**Materials:** Cu lines/vias, TEOS dielectric, Si Substrate  
**Geometry:**  $t=0.5\mu\text{m}$ ,  $h_s=525\mu\text{m}$ ,  $f_l=b/d=0.5$ ,  $V=2.5\mu\text{m}$ ,  $f_v=\pi R^2/bV$   
**Criterion:**  $\alpha=3$ ,  $\sigma_y=293\text{MPa}$  (using Hall-Petch)

**FIG. 8**



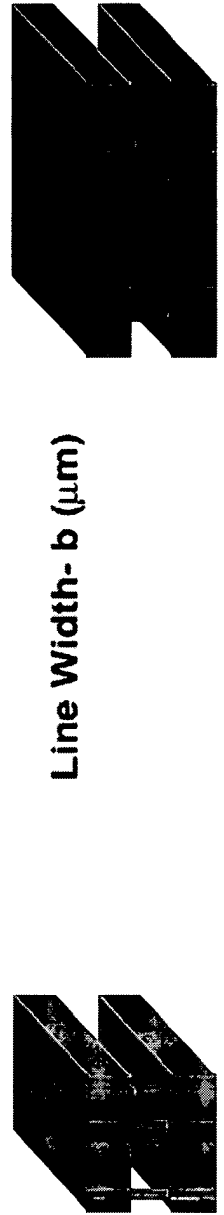
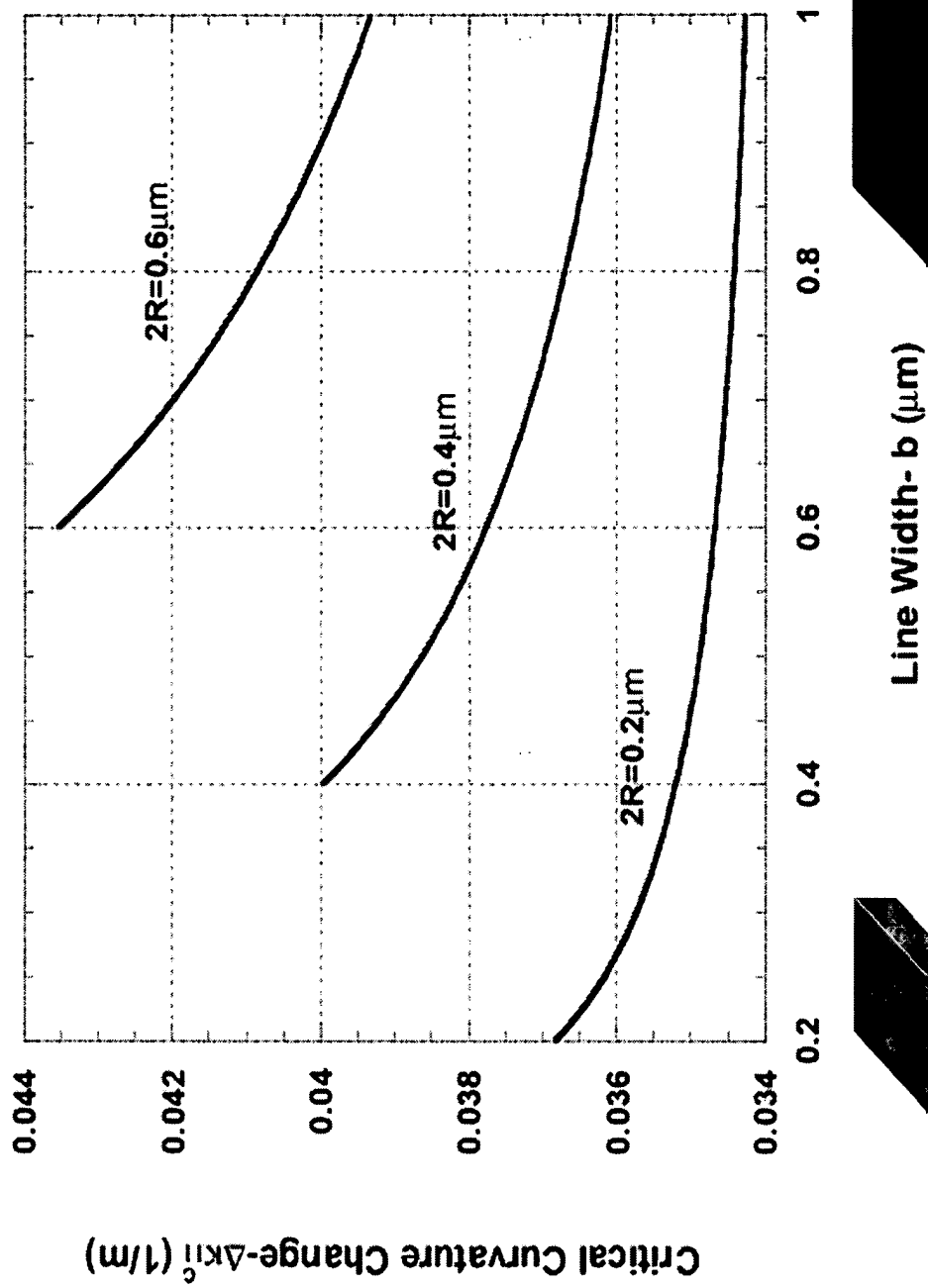
**Materials:** Cu lines/vias, TEOS dielectric, Si Substrate  
**Geometry:**  $t=0.5\mu\text{m}$ ,  $h_s=525\mu\text{m}$ ,  $f_l=b/d=0.5$ ,  $2R=0.4\mu\text{m}$ ,  $f_v=\pi R^2/bV$   
**Criterion:**  $\alpha=3$ ,  $\sigma_y=293\text{MPa}$  (using Hall-Petch)

**FIG. 9**

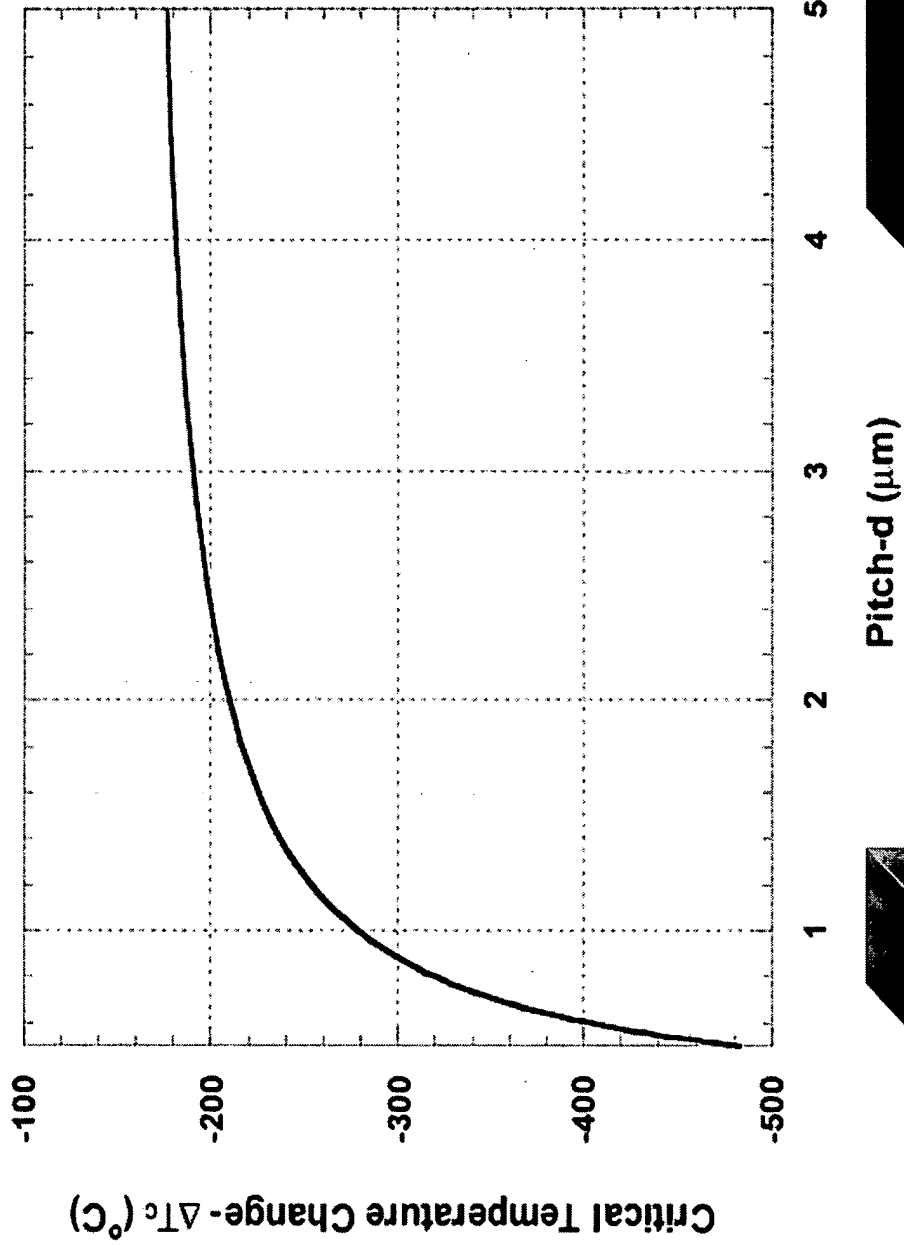


**Materials:** Cu lines/vias, TEOS dielectric, Si Substrate  
**Geometry:**  $t=0.5\mu\text{m}$ ,  $h_s=525\mu\text{m}$ ,  $f_l=b/d=0.5$ ,  $V=2.5\mu\text{m}$ ,  $f_v=\pi R^2/bV$   
**Criterion:**  $\alpha=3$ ,  $\sigma_y=293\text{MPa}$  (using Hall-Petch)

**FIG. 10**

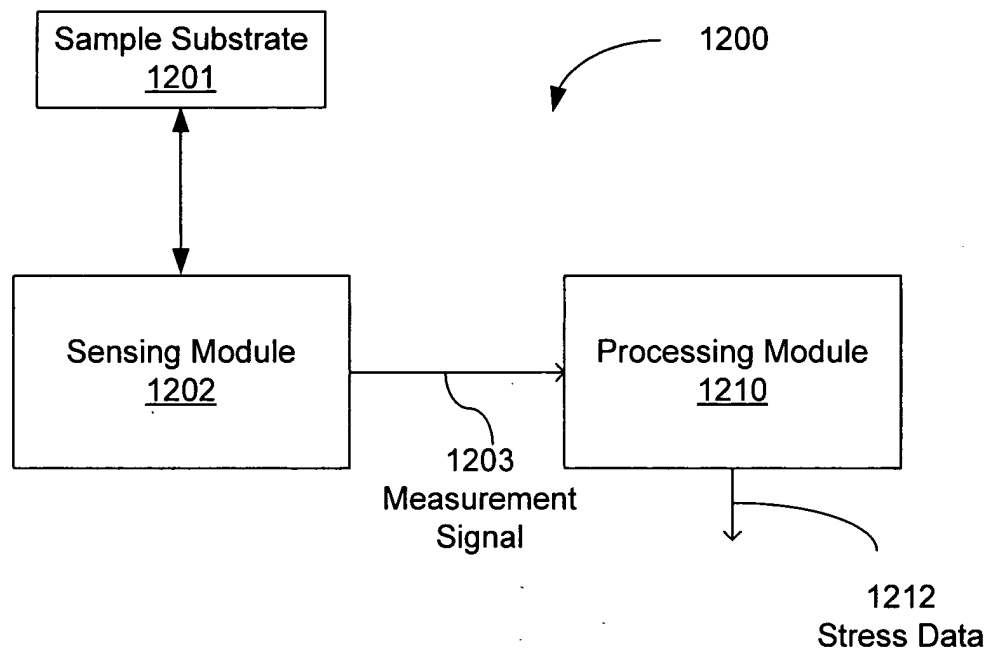


**Materials:** Cu lines/vias, TEOS dielectric, Si Substrate  
**Geometry:**  $t=0.5\mu\text{m}$ ,  $h_s=525\mu\text{m}$ ,  $b=0.4\mu\text{m}$ ,  $f_l=b/d$ ,  $2R=0.4\mu\text{m}$ ,  $V=2.5\mu\text{m}$ ,  $f_v=\pi R^2/bV=0.125$   
**Criterion:**  $\alpha=3$ ,  $\sigma_y=293\text{MPa}$  (using Hall-Petch)

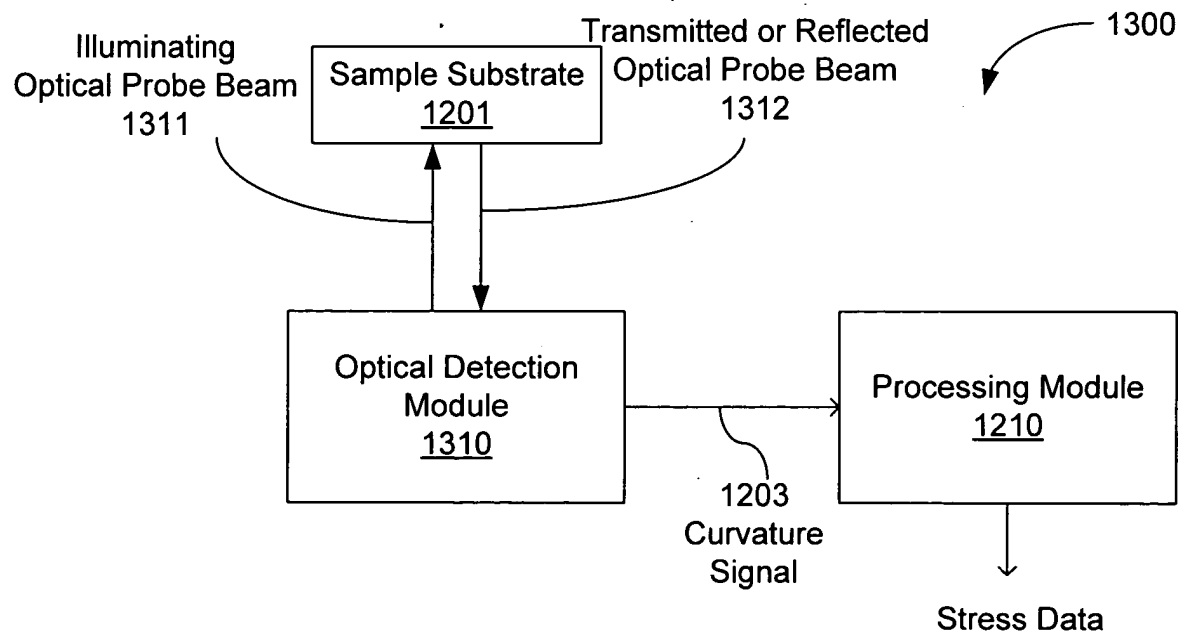


**FIG. 11**

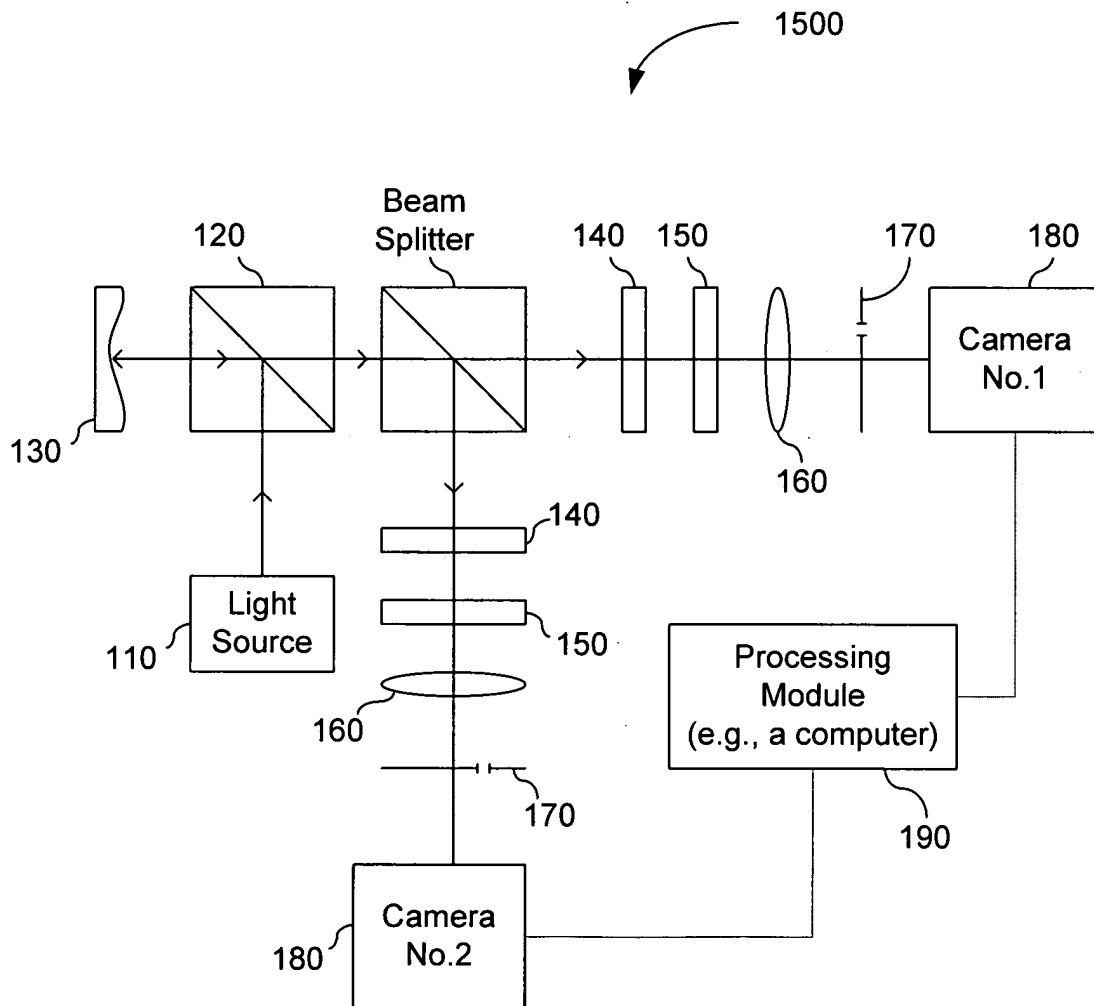
**FIG. 12**



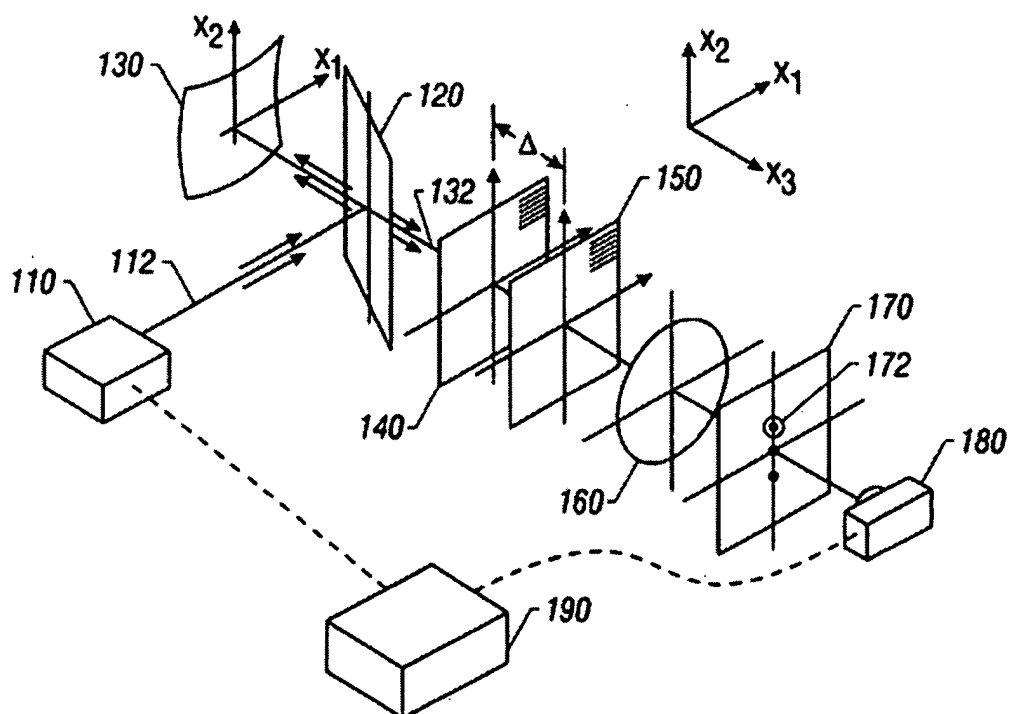
**FIG. 13**



**FIG. 15**



**FIG. 14**



**FIG. 16**

